

HSB88WK

Silicon Schottky Barrier Diode for High Speed Switching

REJ03G0588-0100
(Previous: ADE-208-1042)
Rev.1.00
Mar 31, 2005

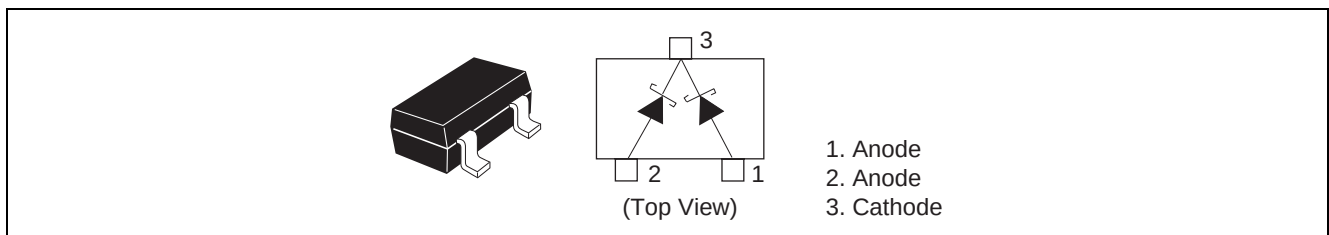
Features

- Proof against high voltage.
- CMPAK package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
HSB88WK	C4	CMPAK	PTSP0003ZB-A (CMPAK)

Pin Arrangement



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Reverse voltage	V_R	10	V
Average rectified current	I_O * ¹	15	mA
Junction temperature	T_j	125	°C
Storage temperature	T_{stg}	-55 to +125	°C

Note: 1. Per one device.

Electrical Characteristics *¹

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	V_{F1}	0.350	—	0.420	V	$I_F = 1$ mA
	V_{F2}	0.500	—	0.580		$I_F = 10$ mA
Reverse current	I_{R1}	—	—	0.2	μ A	$V_R = 2$ V
	I_{R2}	—	—	10		$V_R = 10$ V
Capacitance	C	—	—	0.80	pF	$V_R = 0$ V, $f = 1$ MHz
Capacitance deviation	ΔC	—	—	0.10	pF	$V_R = 0$ V, $f = 1$ MHz
Forward voltage deviation	ΔV_F	—	—	10	mV	$I_F = 10$ mA
ESD-Capability ^{*2}	—	30	—	—	V	C = 200 pF, R = 0 Ω , Both forward and reverse direction 1 pulse.

Notes: 1. Per one device.

2. Failure criterion ; $I_R > 0.4 \mu$ A at $V_R = 2$ V

Main Characteristic

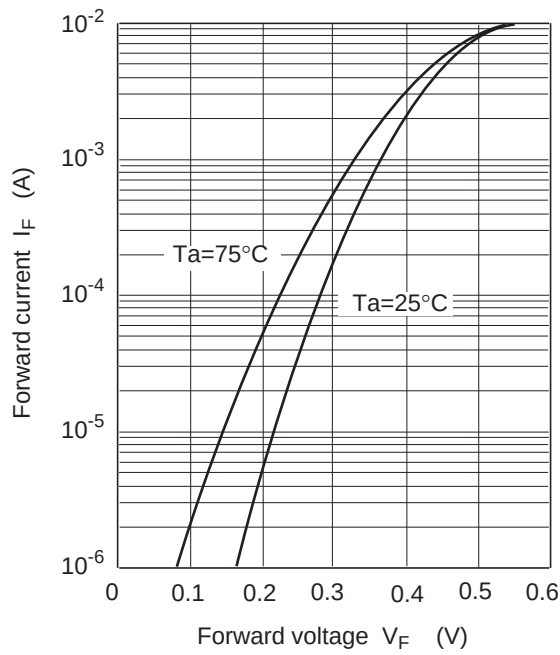


Fig.1 Forward current vs. Forward voltage

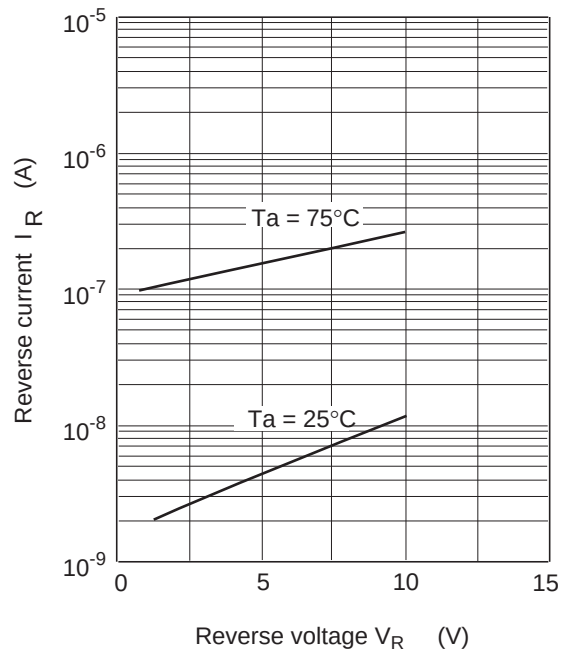


Fig.2 Reverse current vs. Reverse voltage

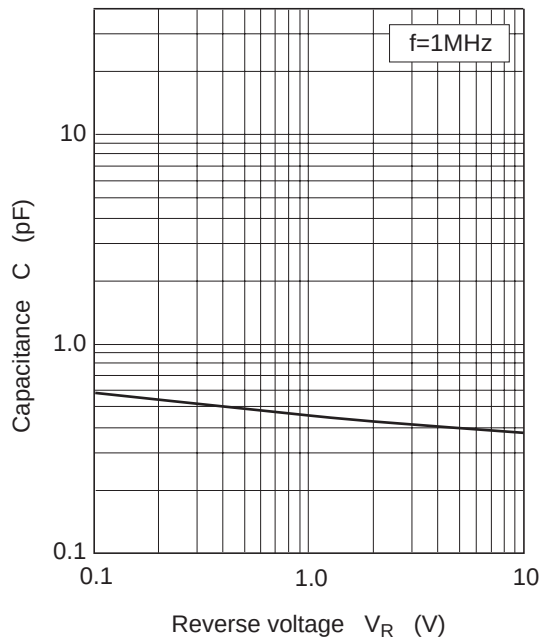
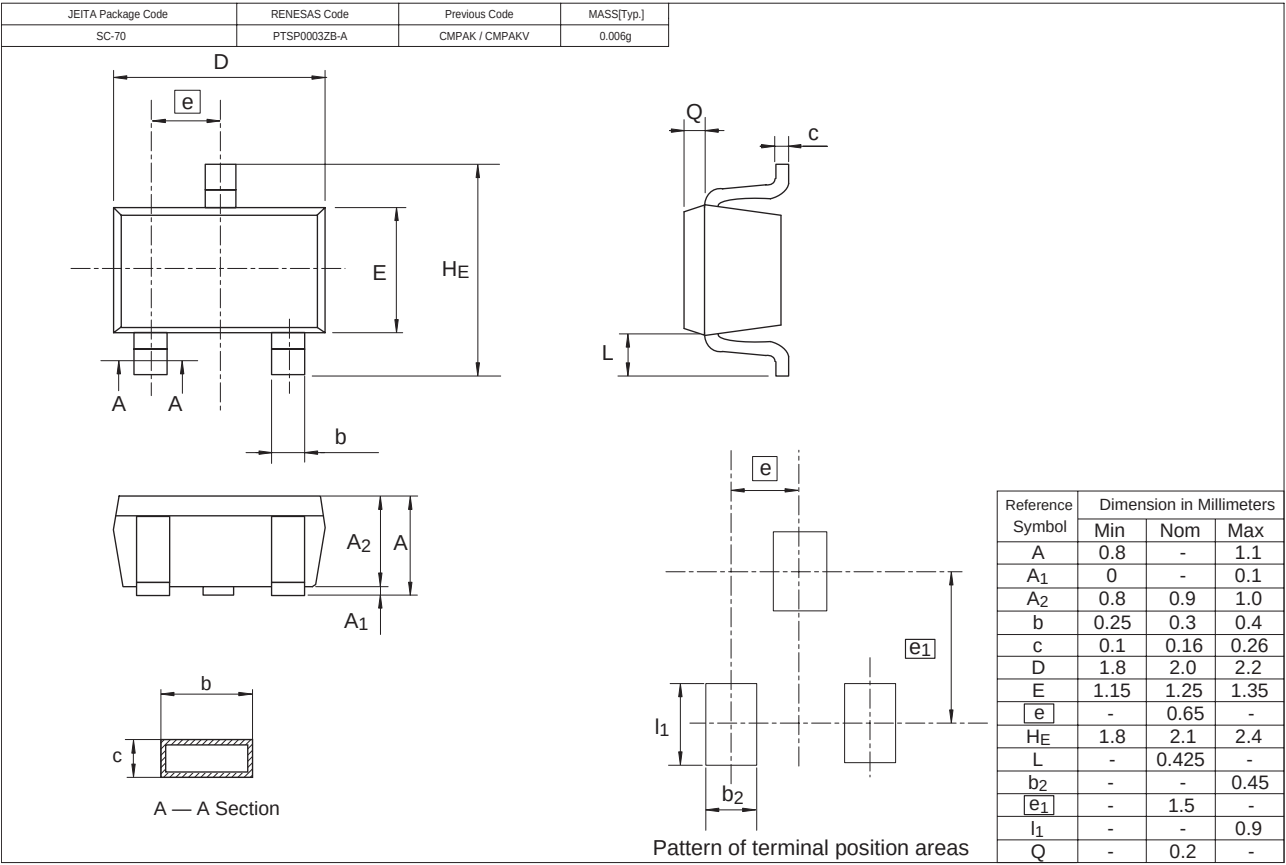


Fig.3 Capacitance vs. Reverse voltage

Package Dimensions



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